



Product Summary

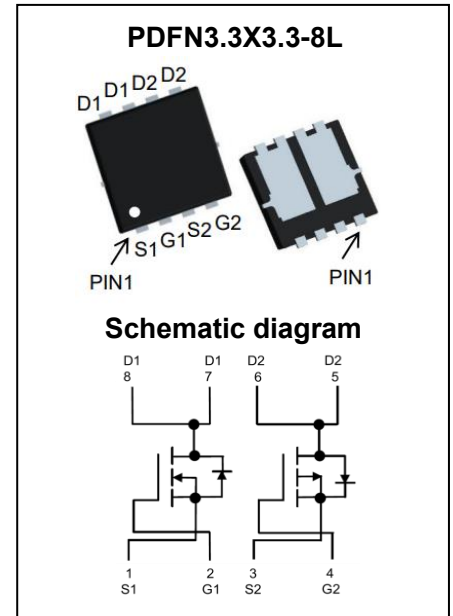
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	10m Ω @10V	31A
	17m Ω @4.5V	
-30V	12m Ω @-10V	-30A
	17m Ω @-4.5V	

Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge

Application

- Load Switch
- DC/DC Converter



MARKING:



30NP16 = Device Code
XX = Date Code
Solid dot = Green Device

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Value	Unit	
Drain - Source Voltage	V_{DS}	30	-30	V	
Gate - Source Voltage	V_{GS}	± 20	± 20	V	
Continuous Drain Current ^{1,5}	$T_A = 25^\circ\text{C}$	I_D	14	-14	A
	$T_C = 25^\circ\text{C}$	I_D	31	-30	A
	$T_C = 100^\circ\text{C}$	I_D	20	-20	A
Pulsed Drain Current ²	I_{DM}	120	-120	A	
Power Dissipation ⁴	$T_C = 25^\circ\text{C}$	P_D	13.6		W
	$T_A = 25^\circ\text{C}$		2.8		
Thermal Resistance from Junction to Ambient ⁵	$R_{\theta JA}$	44.6		$^\circ\text{C/W}$	
Thermal Resistance from Junction to Case	$R_{\theta JC}$	9.2		$^\circ\text{C/W}$	
Junction Temperature	T_J	150	150	$^\circ\text{C}$	
Storage Temperature	T_{STG}	-55~ +150	-55~ +150	$^\circ\text{C}$	

MOSFET ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

NMOS:

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
On Characteristics³						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	3	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5A$		10	14	m Ω
		$V_{GS} = 4.5V, I_D = 5A$		17	26	
Forward transconductance	g_{FS}	$I_S = 5A, V_{GS} = 0V$	10	43		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$		968		pF
Output Capacitance	C_{oss}			146		
Reverse Transfer Capacitance	C_{rss}			136		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 15V, V_{GS} = 10V, I_D = 10A$		13		nC
Gate-source Charge	Q_{gs}			3		
Gate-drain Charge	Q_{gd}			4.5		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V, V_{GS} = 10V, R_L = 1.8\Omega, R_G = 1.8\Omega$			10	ns
Turn-on Rise Time	t_r				8	
Turn-off Delay Time	$t_{d(off)}$				30	
Turn-off Fall Time	t_f				5	
Source - Drain Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	$V_{GS} = 0V, I_S = 5A$			1.2	V

MOSFET ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PMOS:

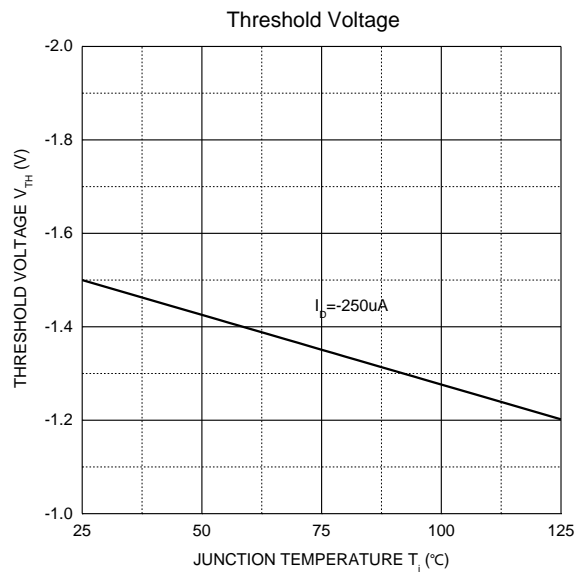
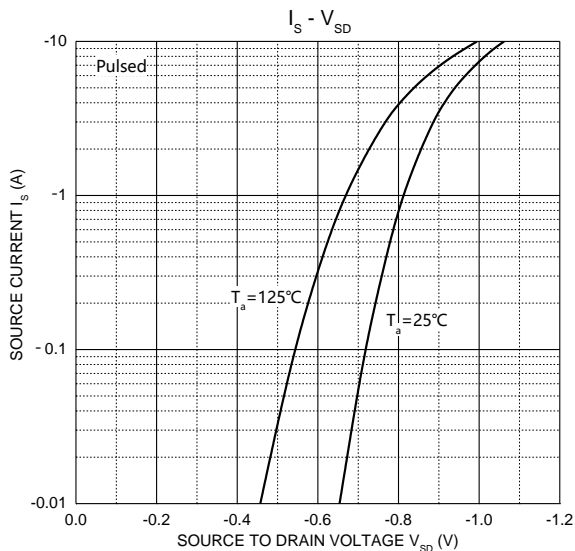
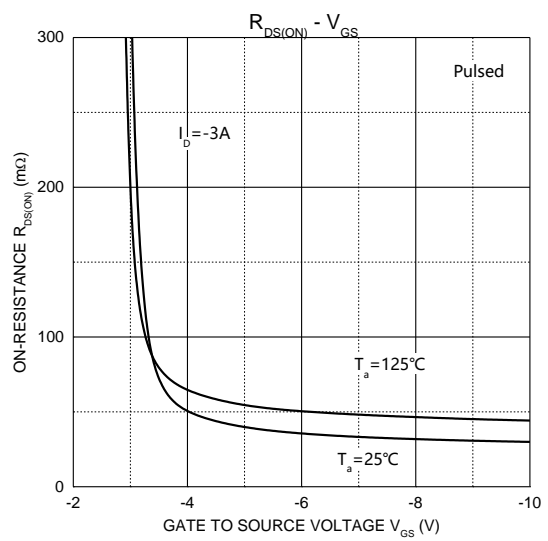
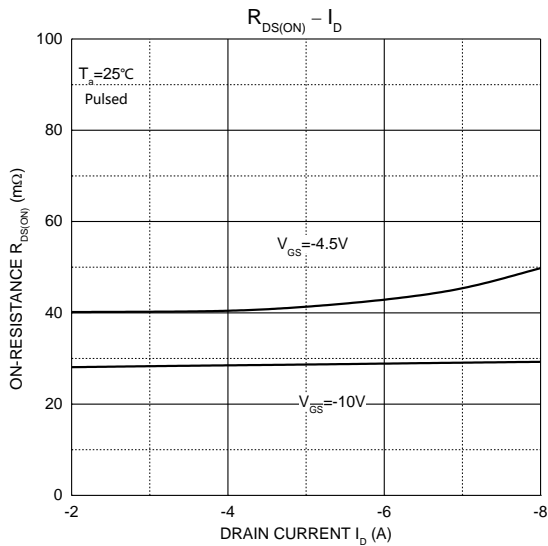
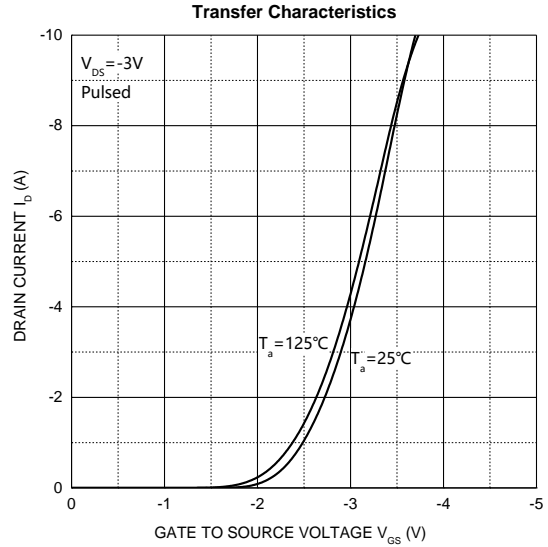
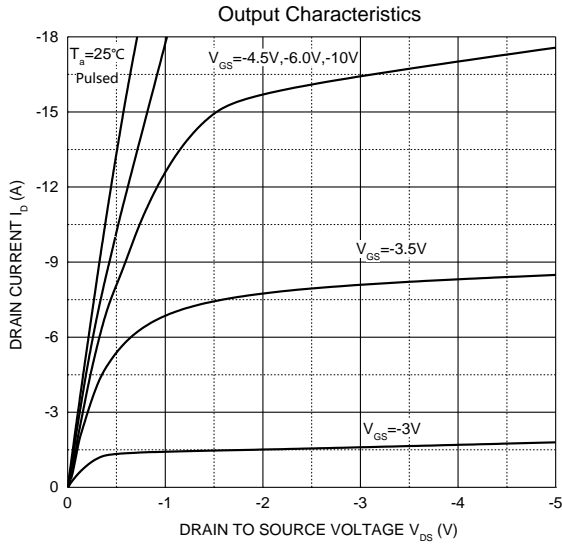
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24V, V_{GS} = 0V$			-1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
On Characteristics³						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.5	-3	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -5A$		12	16	m Ω
		$V_{GS} = -4.5V, I_D = -5A$		17	26	
Forward transconductance	g_{FS}	$I_S = -5A, V_{GS} = 0V$	5	16		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		1350		pF
Output Capacitance	C_{oss}			215		
Reverse Transfer Capacitance	C_{rss}			185		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = -15V, V_{GS} = -4.5V, I_D = -9.1A$		15		nC
Gate-source Charge	Q_{gs}			4		
Gate-drain Charge	Q_{gd}			7.5		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -15V, V_{GS} = -10V, R_L = 15\Omega, R_G = 1\Omega$			15	ns
Turn-on Rise Time	t_r				15	
Turn-off Delay Time	$t_{d(off)}$				70	
Turn-off Fall Time	t_f				25	
Source - Drain Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	$V_{GS} = 0V, I_S = -5A$			-1.2	V

Notes :

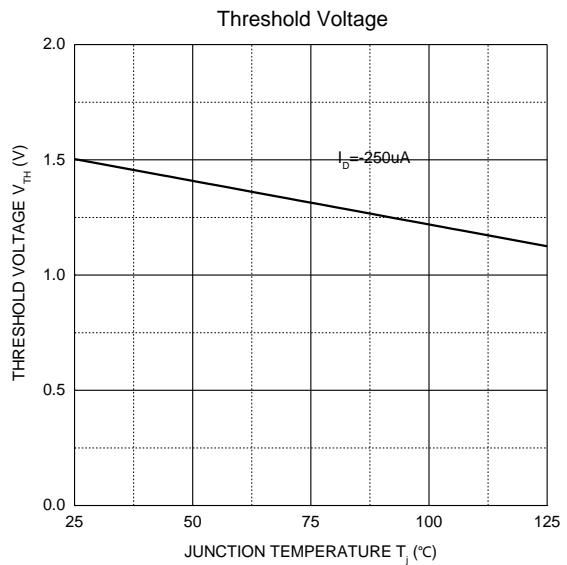
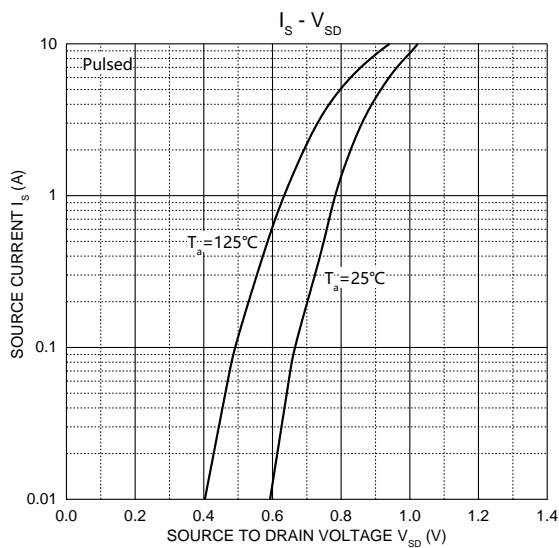
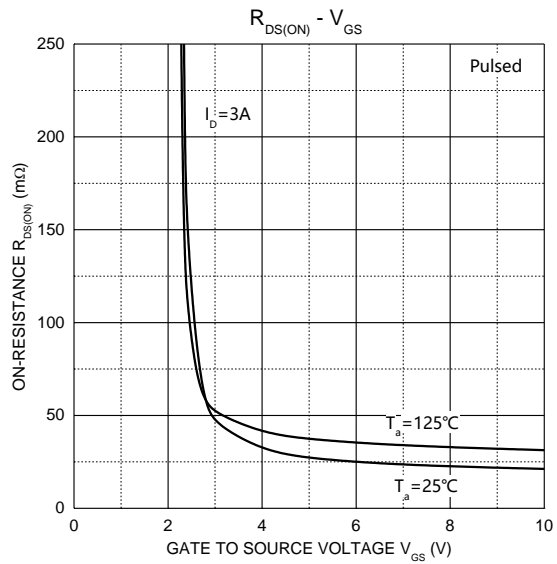
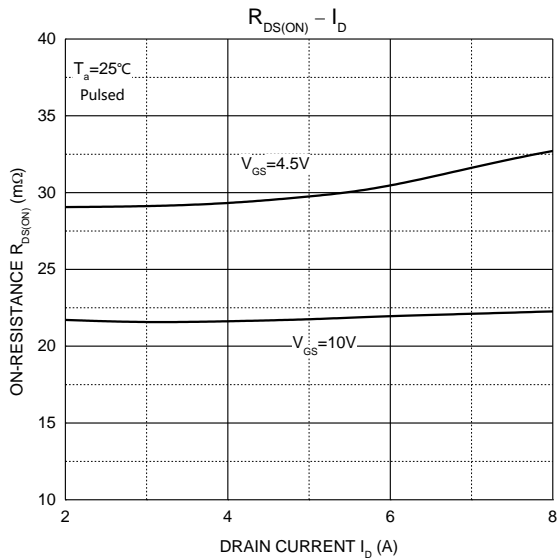
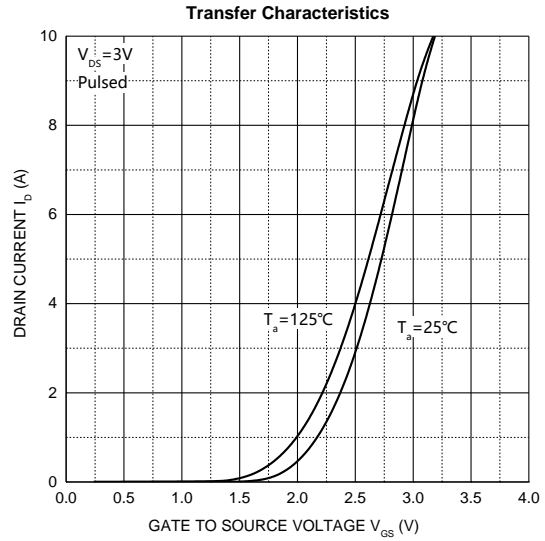
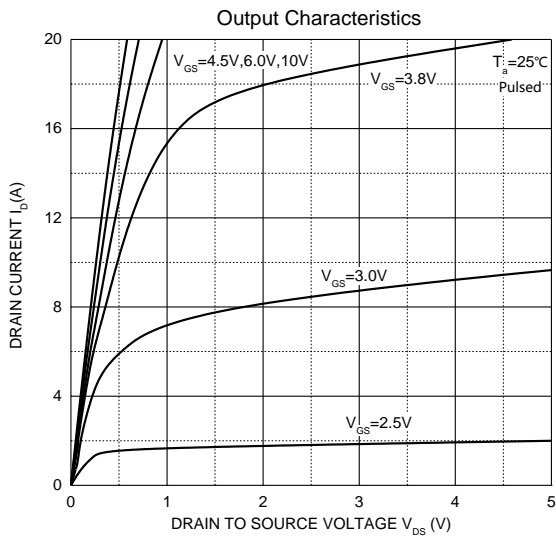
- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.
- 5.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Electrical and Thermal Characteristics

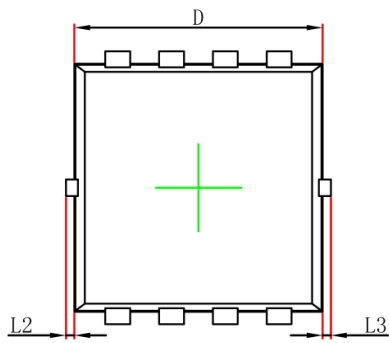
P-Channel MOS



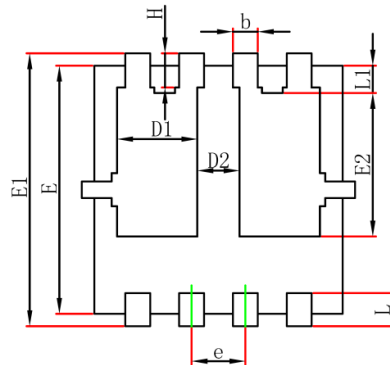
N-Channel MOS



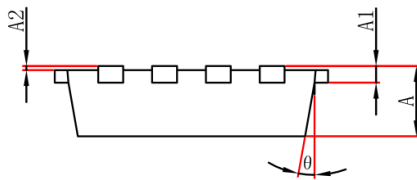
PDFN3.3X3.3-8L Package Information



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°